

LP-ISM010

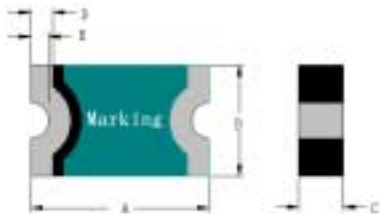
Features

- Very small size of 0805
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV



Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-ISM010	2.20	1.50	1.00	0.10	0.20



Electrical Characteristics

Part number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} Current(A) Time(S)	Pd_{typ} (W)	R_{min} ()	R_{1max} ()
LP-ISM010	0.10	0.30	15.0	40.0	0.50 1.50	0.5	1.00	6.00

I_H =Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T =Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

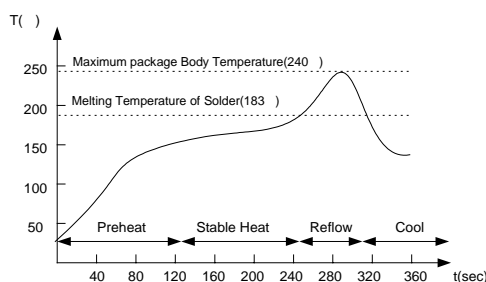
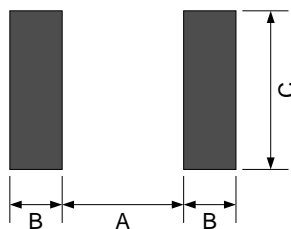
I_{max} =Maximum fault current device can withstand without damage at rated voltage.

T_{trip} =Maximum time to trip(s) at assigned current.

R_{min} =Minimum device resistance at 25 °C prior to tripping.

R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-ISM010	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.